

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions, and listings, of claims in the application:

Claims:

Claim 1 (Currently amended): A holder for an electronic module for connection to a printed circuit board in an electronic equipment, the holder being configured arranged to receive the electronic module, the holder comprising:

~~and having a portion provided with a portion with at least one hole therethrough, wherein the at least one hole is positioned arranged to provide access through the holder to the printed circuit board for testing; and~~

~~the holder is further provided with a conductive layer on a surface of the portion with the at least one hole therethrough for positioning adjacent the printed circuitry board.~~

Claim 2 (Currently amended): The holder of claim 1 wherein the at least one hole is positioned arranged to be covered by the electronic module when positioned in the holder.

Claim 3 (Currently amended): The holder of claim 1 wherein the holder includes is provided with a plurality of holes therethrough.

Claim 4 (Currently amended): The holder of claim 1 wherein the holder is arranged configured to be mounted on the printed circuitry board by one of the group consisting of: A or B, wherein:

A comprises surface mount technology[[],]; and

B comprises plated through hole technology.

Claim 5 (Cancelled)

Claim 6 (Previously presented): The holder of claim 1 wherein the electronic module comprises a subscriber identification module.

Claim 7 (Previously presented): The holder of claim 1 wherein the electronic equipment comprises wireless communication equipment.

Claim 8 (Previously presented): The holder of claim 7 wherein the wireless communication equipment comprises a portable modem.

Claim 9 (Cancelled)

Claim 10 (Previously presented): The holder of claim 1 wherein the holder is of moulded plastics material.

Claim 11 (Currently amended): A method of assembling a holder for an electronic module on a printed circuit board in an electronic equipment, the method comprising:

providing the printed circuit board;

providing a holder for the electronic module for mounting to the printed circuit board, the holder being arranged configured to receive the electronic module and having a portion provided with at least one hole to provide access through the holder [[of]]to the printed circuit board for testing purposes;

providing ~~the holder~~ with a conductive layer on a surface of the portion with the at least one hole for positioning adjacent the printed circuit board; and

mounting the holder on the printed circuit board.

Claim 12 (Previously presented): The method of claim 11 further comprising inserting the electronic module in the holder such that at least one hole is covered by the electronic module.

Claim 13 (Previously presented): The method of claim 11 wherein the holder is provided with a plurality of holes therethrough.

Claim 14 (Currently amended): The method of claim 11 wherein the step of mounting comprises mounting the electronic module on the printed circuit board by one of the group consisting of: A or B, wherein:

~~A~~ comprises surface mount technology[[,]]; and

~~B~~ comprises plated through hole technology.

Claim 15 (Cancelled)

Claim 16 (Previously presented): The method of claim 11 wherein the electronic module comprises a subscriber identification module.

Claim 17 (Previously presented): The method of claim 11 wherein the electronic equipment comprises wireless communication equipment.

Claim 18 (Previously presented): The method of claim 17 wherein the wireless communication equipment comprises a portable modem.

Claim 19 (Cancelled)

Claim 20 (Currently amended): The method of claim 11[[=]] wherein the holder is moulded of plastics material.

Claim 21 (Cancelled)

Claim 22 (Previously presented): An electronic circuit having mounted thereon the holder of claim 1.

Claim 23 (Cancelled)

Claim 24 (Cancelled)